




DOCKET NO: VSEA 16-99

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Grant Kenji Larsen  
Serial No: 09/676,548  
Confirmation No: 2719  
Filed: September 29, 2000  
For: SURFACE STRUCTURE AND METHOD OF MAKING, AND  
ELECTROSTATIC WAFER CLAMP INCORPORATING  
SURFACE STRUCUTRE  
Examiner: Stephen W. Jackson  
Art Unit: 2836

**CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)**

The undersigned hereby certifies that this document is being placed in the United States mail with first-class postage attached, addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the 20<sup>th</sup> day of January, 2004.

  
Cheryl Purcell

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**Ex Parte Quayle Response**

In response to the Office Action mailed September 17, 2003, the following response is submitted in connection with the above-identified application.

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